Product Change Notification: CAAN-14GCEK666

Date:

18-Sep-2025

Product Category:

8-Bit Microcontrollers, Memory

Notification Subject:

CCB 7829 Initial Notice: Qualification of MMT as an additional assembly site for selected 25AA1024, 25AA512, 25AA640A, 25LC1024, 25LC256, 25LC512, PIC12F635 and PIC12F683 device families available in 8L DFN-S (6x5x0.9mm) package.

Affected CPNs:

CAAN-14GCEK666_Affected_CPN_09182025.pdf
CAAN-14GCEK666_Affected_CPN_09182025.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected 25AA1024, 25AA512, 25AA640A, 25LC1024, 25LC256, 25LC512, PIC12F635 and PIC12F683 device families available in 8L DFN-S (6x5x0.9mm) package.

Pre and Post Summary Changes:

	Pre Change		**Post Change**		
Assembly Site	UTAC Thai Limited LTD. (UTL-1) (NSEB)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	UTAC Thai Limited LTD. (UTL-1) (NSEB)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Microchip Technology Thailand (Branch) (MMT)

Wire Material	Au	Au	Au	Au	CuPdAu
Die Attach Material	8600 (PFAS)	AMK-06 (PFAS-free)	8600 (PFAS)	AMK-06 (PFAS-free)	QMI519 (PFAS-free)
Molding Compound Material	G700LTD	G700	G700LTD	G700	G700LTD
Lead-Frame Material	EFTEC-64T	C194	EFTEC-64T	C194	C194
Lead-Frame Lead Lock	Dimple	Half-etch	Dimple	Half-etch	Dimple
Lead-Frame Comparison	See Pre and Post Change Comparison				
DAP Surface Prep	Ag Ring	Ag	Ag Ring	Ag	Bare Cu

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance and manufacturability by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: October 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2025					**October 2025**			
Work Week	36	37	38	39	40	41	42	43	44
Initial PCN Issue Date			X						
Qual Report Availability						X			
Final PCN Issue Date						X			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: September 18, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf
PCN_CAAN-14GCEK666_Pre and Post Change Summary.pdf
PCN_CAAN-14GCEK666_Qualification Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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